

Micro MINI E0C6002

4-bit Single Chip Microcomputer



- E0C6200B Core CPU
- Low Voltage and Low Power
- Built-in LCD Driver
- Built-in R/F Converter
- Low Cost Performance

■ DESCRIPTION

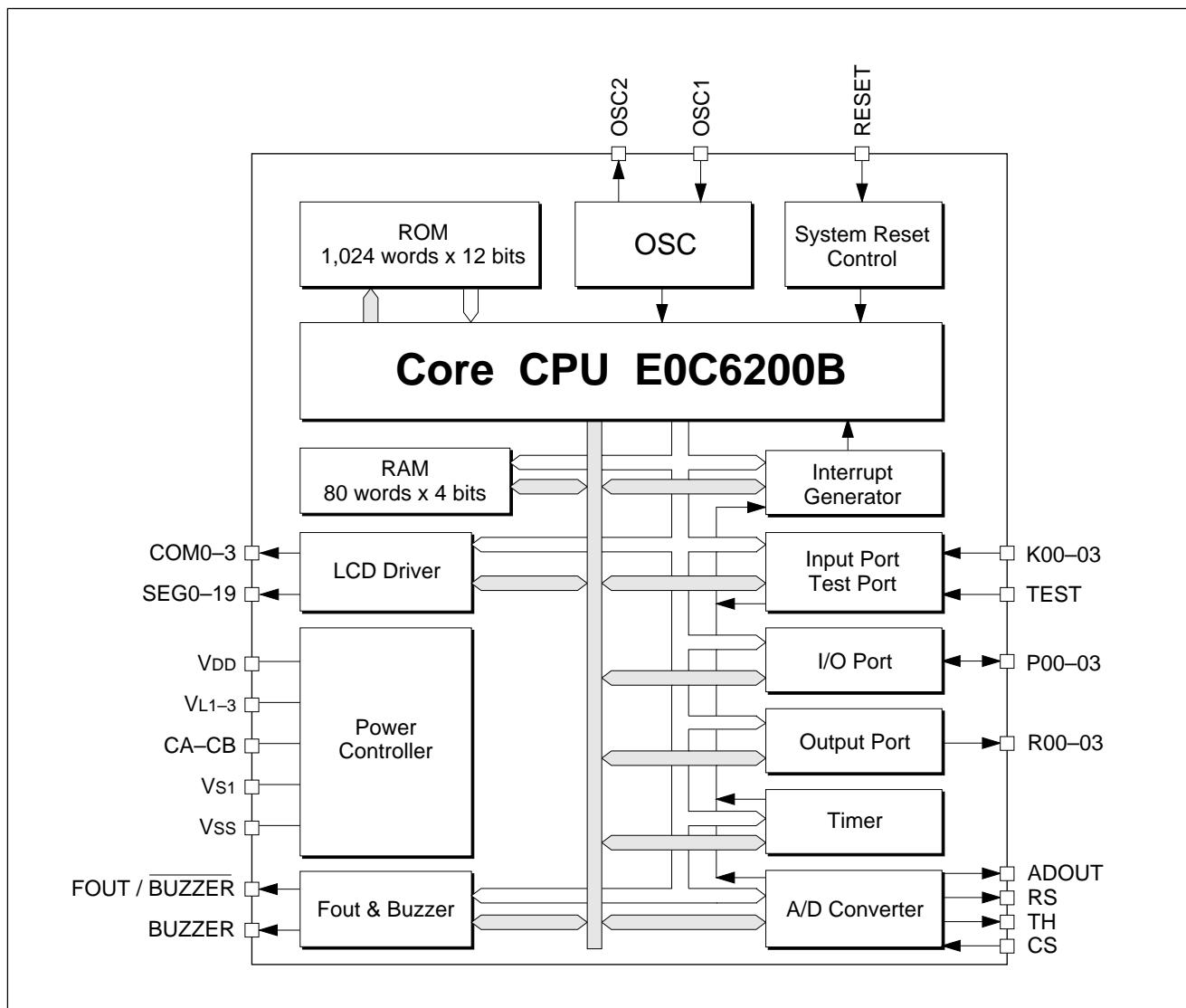
Micro MINI "E0C6002" is a single chip microcomputer for battery-driven products with 7-segment LCD display. It achieves low cost performance, and is suitable for a product added some feature instead of standard IC. It consists that Seiko Epson's original core CPU E0C6200B, LCD driver (20 segments × 4 commons), 80 words RAM, 1K words ROM, clock timer and so on.

■ FEATURES

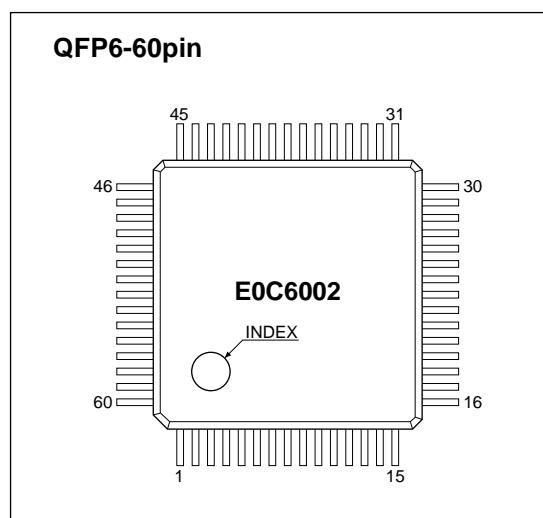
- CMOS LSI 4-bit parallel processing
- Clock 32.768kHz (X'tal or CR oscillation by mask option)
- Instruction set 100 instructions
- ROM capacity 1K × 12 bits
- RAM capacity 80 × 4 bits
- I/O port
 - I: 4 bits (with pull-down resistor selectable by mask option)
 - O: 4 bits (buzzer output possible by mask option)
 - I/O: 4 bits
- Supply voltage detector (SVD) No support
- Clock timer 1ch.
- LCD driver 20 segments × 4/3/2 commons
- R/F converter 1ch.
- Interrupt
 - External : Key interrupt 1 line
 - Internal : Clock timer interrupt 1 line
- Operation voltage
 - 1.2 to 1.8V (E0C60L02)
 - 2.4 to 3.6V (E0C6002)
- Power consumption
 - 1.0µA (32.768kHz X'tal, 3.0V, HALT)
 - 2.5µA (32.768kHz X'tal, 3.0V, RUN)
- Package Die form (pad pitch = 130µm) or QFP6-60pin

E0C6002

■ BLOCK DIAGRAM



■ PIN CONFIGURATION



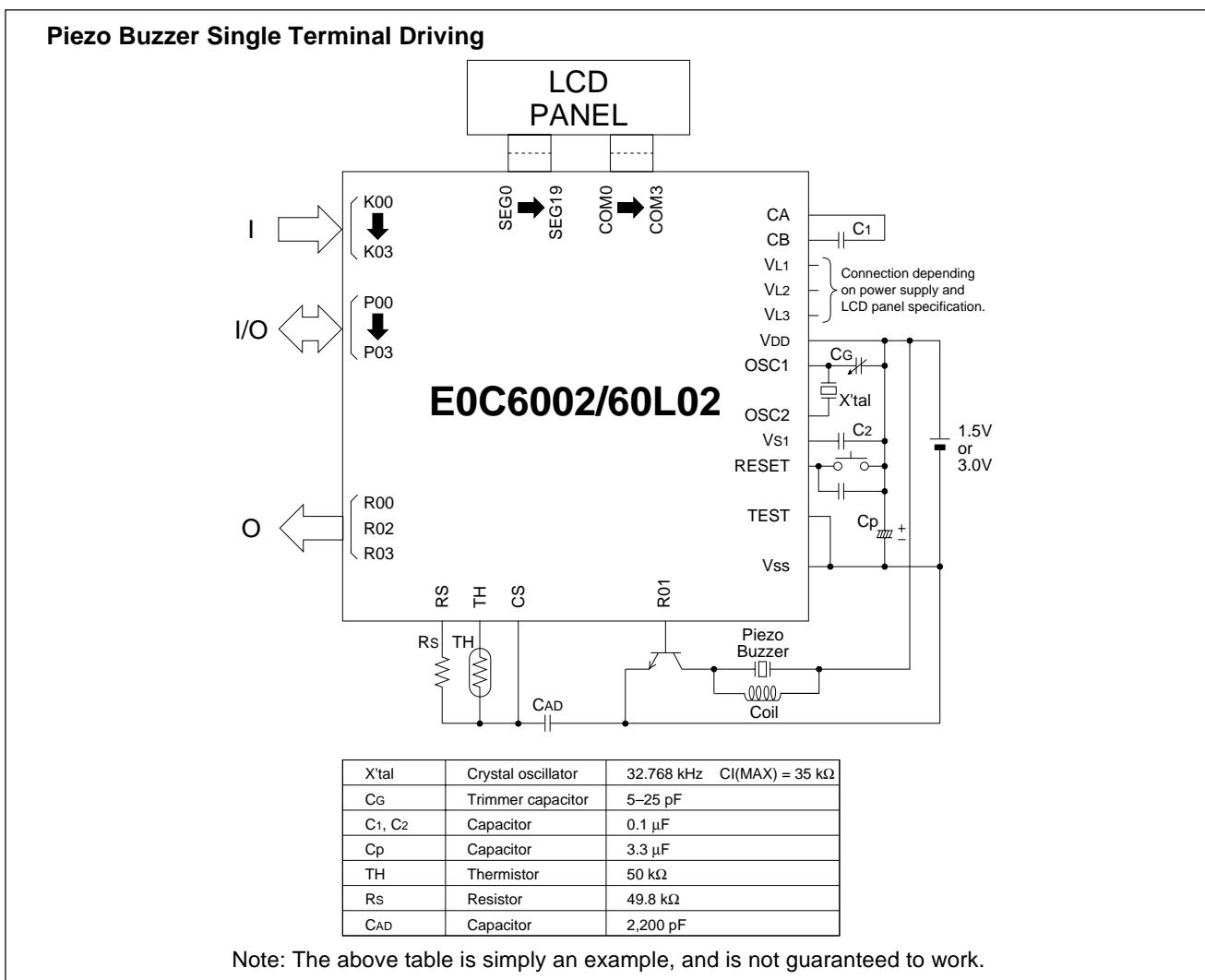
Pin No.	Pin name						
1	SEG0	16	N.C.	31	N.C.	46	N.C.
2	SEG1	17	TEST	32	VL3	47	K00
3	SEG2	18	RESET	33	VL2	48	K01
4	SEG3	19	SEG12	34	VL1	49	K02
5	SEG4	20	SEG13	35	CA	50	K03
6	SEG5	21	SEG14	36	CB	51	R00
7	SEG6	22	SEG15	37	Vss	52	R01
8	SEG7	23	SEG16	38	Vdd	53	R02
9	SEG8	24	SEG17	39	OSC1	54	R03
10	SEG9	25	SEG18	40	OSC2	55	RS
11	SEG10	26	SEG19	41	Vs1	56	TH
12	SEG11	27	COM0	42	P00	57	CS
13	N.C.	28	COM1	43	P01	58	ADOUT
14	N.C.	29	COM2	44	P02	59	N.C.
15	N.C.	30	COM3	45	P03	60	N.C.

N.C. : No Connection

■ PIN DESCRIPTION

Pin name	Pin No.	In/Out	Function
VDD	38	(I)	Power source (+) terminal
Vss	37	(I)	Power source (-) terminal
Vs1	41	O	Oscillation and internal logic system regulated voltage output terminal
VL1	34	O	LCD system regulated voltage output terminal
VL2	33	O	LCD system booster output terminal
VL3	32	O	LCD system booster output terminal
CA, CB	35, 36	-	Booster capacitor connecting terminal
OSC1	39	I	Crystal or CR oscillation input terminal
OSC2	40	O	Crystal or CR oscillation output terminal
K00-K03	47-50	I	Input terminal
P00-P03	42-45	I/O	I/O terminal
R00-R03	51-54	O	Output terminal
SEG0-19	1-12 19-26	O	LCD segment output terminal (convertible to DC output terminal by mask option)
COM0-3	27-30	O	LCD common output terminal
CS	57	I	A/D converter CR oscillation input terminal
RS	55	O	A/D converter CR oscillation output terminal
TH	56	O	A/D converter CR oscillation output terminal
ADOUT	58	O	A/D converter oscillation frequency output terminal
RESET	18	I	Initial setting input terminal
TEST	17	I	Test input terminal

■ BASIC EXTERNAL CONNECTION DIAGRAM



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■ ELECTRICAL CHARACTERISTICS

● Absolute Maximum Ratings

(V _{DD} =0V)			
Rating	Symbol	Value	Unit
Power voltage	V _{SS}	-5.0 to 0.5	V
Input voltage (1)	V _I	V _{SS} - 0.3 to 0.5	V
Input voltage (2)	V _{IOSC}	V _{SS} - 0.3 to 0.5	V
Operating temperature	T _{OPR}	-20 to 70	°C
Storage temperature	T _{STG}	-65 to 150	°C
Soldering temperature / Time	T _{SOL}	260°C, 10sec (lead section)	—
Allowable dissipation *1	P _D	250	mW

*1: In case of plastic package (QFP6-60pin).

● Recommended Operating Conditions

E0C6002

(Ta=-20 to 70°C)						
Condition	Symbol	Remark	Min.	Typ.	Max.	Unit
Power voltage	V _{SS}	V _{DD} =0V	-3.5	-3.0	-1.8	V
Oscillation frequency	f _{OSC1}	Crystal oscillation		32.768		kHz
	f _{OSC2}	CR oscillation, R=420kΩ		65	80	kHz
Booster capacitor	C ₁		0.1			μF
Capacitor between V _{DD} and V _{S1}	C ₂		0.1			μF

E0C60L02

(Ta=-20 to 70°C)						
Condition	Symbol	Remark	Min.	Typ.	Max.	Unit
Power voltage	V _{SS}	V _{DD} =0V *3	-2.0	-1.5	-1.2	V
		V _{DD} =0V, With software correspondence *1	-2.0	-1.5	-0.9 *2	V
Oscillation frequency	f _{OSC1}	Crystal oscillation		32.768		kHz
	f _{OSC2}	CR oscillation, R=420kΩ		65	80	kHz
Booster capacitor	C ₁		0.1			μF
Capacitor between V _{DD} and V _{S1}	C ₂		0.1			μF

*1: When switching to the heavy load protection mode.

*2: The voltage which can be displayed on the LCD panel will differ according to the characteristics of the LCD panel.

*3: When there is no software correspondence during CR oscillation or crystal oscillation.

● DC Characteristics

E0C6002

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-3.0V, fosc=32.768kHz, Ta=25°C, V_{S1}/V_{L1}-V_{L3} are internal voltage, C₁=C₂=0.1μF)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
High level input voltage (1)	V _{IH1}	K00-K03, P00-P03	0.2•V _{SS}		0	V
High level input voltage (2)	V _{IH2}	RESET, TEST	0.15•V _{SS}		0	V
Low level input voltage (1)	V _{IL1}	K00-K03, P00-P03	V _{SS}		0.8•V _{SS}	V
Low level input voltage (2)	V _{IL2}	RESET, TEST	V _{SS}		0.85•V _{SS}	V
High level input current (1)	I _{IH1}	V _{IH1} =0V, No pull down resistor	K00-K03, P00-P03	0	0.5	μA
High level input current (2)	I _{IH2}	V _{IH2} =0V, With pull down resistor	K00-K03	5	16	μA
High level input current (3)	I _{IH3}	V _{IH3} =0V, With pull down resistor	P00-P03 RESET, TEST	30	100	μA
Low level input current	I _{IL}	V _{IL} =V _{SS}	K00-K03, P00-P03 RESET, TEST	-0.5	0	μA
High level output current (1)	I _{OH1}	V _{OH1} =0.1•V _{SS}	R02, R03, P00-P03		-1.0	mA
High level output current (2)	I _{OH2}	V _{OH2} =0.1•V _{SS} (built-in protection resistance)	R00, R01		-1.0	mA
High level output current (3)	I _{OH3}	V _{OH3} =-1.0V	ADOUT		-1.0	mA
Low level output current (1)	I _{OL1}	V _{OL1} =0.9•V _{SS}	R02, R03, P00-P03	3.0		mA
Low level output current (2)	I _{OL2}	V _{OL2} =0.9•V _{SS} (built-in protection resistance)	R00, R01	3.0		mA
Low level output current (3)	I _{OL3}	V _{OL3} =-2.0V	ADOUT	3.0		mA
Common output current	I _{OH4}	V _{OH4} =-0.05V	COM0-COM3		-3	μA
	I _{OL4}	V _{OL4} =V _{L3} +0.05V		3		μA
Segment output current (during LCD output)	I _{OH5}	V _{OH5} =-0.05V	SEG0-SEG19		-3	μA
	I _{OL5}	V _{OL5} =V _{L3} +0.05V		3		μA
Segment output current (during DC output)	I _{OH6}	V _{OH6} =0.1•V _{SS}	SEG0-SEG19		-300	μA
	I _{OL6}	V _{OL6} =0.9•V _{SS}		300		μA

E0C60L02

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-1.5V, fosc=32.768kHz, Ta=25°C, V_{S1}/V_{L1}-V_{L3} are internal voltage, C₁=C₂=0.1μF)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
High level input voltage (1)	V _{IH1}	K00-K03, P00-P03	0.2•V _{SS}		0	V
High level input voltage (2)	V _{IH2}	RESET, TEST	0.15•V _{SS}		0	V
Low level input voltage (1)	V _{IL1}	K00-K03, P00-P03	V _{SS}		0.8•V _{SS}	V
Low level input voltage (2)	V _{IL2}	RESET, TEST	V _{SS}		0.85•V _{SS}	V
High level input current (1)	I _{IH1}	V _{IH1} =0V, No pull down resistor	K00-K03, P00-P03	0	0.5	μA
High level input current (2)	I _{IH2}	V _{IH2} =0V, With pull down resistor	K00-K03	2.0	16	μA
High level input current (3)	I _{IH3}	V _{IH3} =0V, With pull down resistor	P00-P03 RESET, TEST	9.0	100	μA
Low level input current	I _{IL}	V _{IL} =V _{SS}	K00-K03, P00-P03 RESET, TEST	-0.5	0	μA
High level output current (1)	I _{OH1}	V _{OH1} =0.1•V _{SS}	R02, R03, P00-P03		-200	μA
High level output current (2)	I _{OH2}	V _{OH2} =0.1•V _{SS} (built-in protection resistance)	R00, R01		-200	μA
High level output current (3)	I _{OH3}	V _{OH3} =-0.5V	ADOUT		-200	μA
Low level output current (1)	I _{OL1}	V _{OL1} =0.9•V _{SS}	R02, R03, P00-P03	700		μA
Low level output current (2)	I _{OL2}	V _{OL2} =0.9•V _{SS} (built-in protection resistance)	R00, R01	700		μA
Low level output current (3)	I _{OL3}	V _{OL3} =-1.0V	ADOUT	700		μA
Common output current	I _{OH4}	V _{OH4} =-0.05V	COM0-COM3		-3	μA
	I _{OL4}	V _{OL4} =V _{L3} +0.05V		3		μA
Segment output current (during LCD output)	I _{OH5}	V _{OH5} =-0.05V	SEG0-SEG19		-3	μA
	I _{OL5}	V _{OL5} =V _{L3} +0.05V		3		μA
Segment output current (during DC output)	I _{OH6}	V _{OH6} =0.1•V _{SS}	SEG0-SEG19		-100	μA
	I _{OL6}	V _{OL6} =0.9•V _{SS}		130		μA

E0C6002

● Analog Circuit Characteristics and Current Consumption

E0C6002 (Normal Operating Mode)

(Unless otherwise specified: VDD=0V, Vss=-3.0V, fosc=32.768kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
 <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)	1/2•VL2 -0.1		1/2•VL2 ×0.9	V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)		Vss		V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3/2•VL2 -0.1		3/2•VL2 ×0.9	V
Power current consumption	IOP	During HALT		1.0	2.5	μA
		During execution	Without panel load	2.5	5.0	μA
		During A/D conversion (HALT)		30	40	μA

E0C6002 (Heavy Load Protection Mode)

(Unless otherwise specified: VDD=0V, Vss=-3.0V, fosc=32.768kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
 <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)	1/2•VL2 -0.1		1/2•VL2 ×0.85	V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)		Vss		V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3/2•VL2 -0.1		3/2•VL2 ×0.85	V
Power current consumption	IOP	During HALT		2.0	5.5	μA
		During execution	Without panel load	5.5	10.0	μA
		During A/D conversion (HALT)		31	41.5	μA

E0C60L02 (Normal Operating Mode)

(Unless otherwise specified: VDD=0V, Vss=-1.5V, fosc=32.768kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
 <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)		Vss		V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)	2•VL1 -0.1		2•VL1 ×0.9	V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3•VL1 -0.1		3•VL1 ×0.9	V
Power current consumption	IOP	During HALT		1.0	2.5	μA
		During execution	Without panel load	2.5	5.0	μA
		During A/D conversion (HALT)		30	40	μA

E0C60L02 (Heavy Load Protection Mode)

(Unless otherwise specified: VDD=0V, Vss=-1.5V, fosc=32.768kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
 <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)		Vss		V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)	2•VL1 -0.1		2•VL1 ×0.85	V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3•VL1 -0.1		3•VL1 ×0.85	V
Power current consumption	IOP	During HALT		2.0	5.5	μA
		During execution	Without panel load	5.5	10.0	μA
		During A/D conversion (HALT)		31	41.5	μA

E0C6002 (CR, Normal Operating Mode)

(Unless otherwise specified: VDD=0V, Vss=-3.0V, fosc=65kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
Recommended external resistance for CR oscillation=420kΩ <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)	1/2•VL2 -0.1		1/2•VL2 ×0.9	V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)		Vss		V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3/2•VL2 -0.1		3/2•VL2 ×0.9	V
Power current consumption	IOP	During HALT		8.0	15.0	μA
		During execution	Without panel load	15.0	20.0	μA
		During A/D conversion (HALT)		37	52.5	μA

E0C6002 (CR, Heavy Load Protection Mode)

(Unless otherwise specified: VDD=0V, Vss=-3.0V, fosc=65kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
Recommended external resistance for CR oscillation=420kΩ <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)	1/2•VL2 -0.1		1/2•VL2 ×0.85	V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)		Vss		V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3/2•VL2 -0.1		3/2•VL2 ×0.85	V
Power current consumption	IOP	During HALT		16.0	30.0	μA
		During execution	Without panel load	30.0	40.0	μA
		During A/D conversion (HALT)		45	57.5	μA

E0C60L02 (CR, Normal Operating Mode)

(Unless otherwise specified: VDD=0V, Vss=-1.5V, fosc=65kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
Recommended external resistance for CR oscillation=420kΩ <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)		Vss		V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)	2•VL1 -0.1		2•VL1 ×0.9	V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3•VL1 -0.1		3•VL1 ×0.9	V
Power current consumption	IOP	During HALT		8.0	15.0	μA
		During execution	Without panel load	15.0	20.0	μA
		During A/D conversion (HALT)		37	52.5	μA

E0C60L02 (CR, Heavy Load Protection Mode)

(Unless otherwise specified: VDD=0V, Vss=-1.5V, fosc=65kHz, Ta=25°C, CG=25pF, Vs1/VL1–VL3 are internal voltage, C1=C2=0.1μF
Recommended external resistance for CR oscillation=420kΩ <During A/D conversion: Rs=49.8kΩ, TH=50kΩ, CAD=2,200pF>)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Internal voltage	VL1	Connect 1MΩ load resistor between VDD and VL1 (without panel load)		Vss		V
	VL2	Connect 1MΩ load resistor between VDD and VL2 (without panel load)	2•VL1 -0.1		2•VL1 ×0.85	V
	VL3	Connect 1MΩ load resistor between VDD and VL3 (without panel load)	3•VL1 -0.1		3•VL1 ×0.85	V
Power current consumption	IOP	During HALT		16.0	30.0	μA
		During execution	Without panel load	30.0	40.0	μA
		During A/D conversion (HALT)		45	57.5	μA

E0C6002

● Oscillation Characteristics

Oscillation characteristics will vary according to different conditions. Use the following characteristics are as reference values.

E0C6002

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-3.0V, Crystal: C-002R (Cl=35kΩ), CG=25pF, Cd=built-in, Ta=25°C)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation start voltage	V _{STA}	t _{STA} ≤5sec (V _{SS})	-1.8			V
Oscillation stop voltage	V _{STP}	t _{STP} ≤10sec (V _{SS})	-1.8			V
Built-in capacitance (drain)	C _D	Including the parasitic capacity inside the IC		20		pF
Frequency/voltage deviation	Δf/ΔV	V _{SS} =-1.8 to -3.5V			5	ppm
Frequency/IC deviation	Δf/ΔIC		-10		10	ppm
Frequency adjustment range	Δf/ΔCG	CG=5 to 25pF	40			ppm
Harmonic oscillation start voltage	V _{HHO}	CG=5pF (V _{SS})			-3.6	V
Allowable leak resistance	R _{LEAK}	Between OSC1 and V _{DD} , and between V _{SS} and OSC1	200			MΩ

E0C60L02

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-1.5V, Crystal: C-002R (Cl=35kΩ), CG=25pF, Cd=built-in, Ta=25°C)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation start voltage	V _{STA}	t _{STA} ≤5sec (V _{SS})	-1.2			V
Oscillation stop voltage	V _{STP}	t _{STP} ≤10sec (V _{SS})	-1.2			V
Built-in capacitance (drain)	C _D	Including the parasitic capacity inside the IC		20		pF
Frequency/voltage deviation	Δf/ΔV	V _{SS} =-1.2 to -2.0V (-0.9) *1			5	ppm
Frequency/IC deviation	Δf/ΔIC		-10		10	ppm
Frequency adjustment range	Δf/ΔCG	CG=5 to 25pF	40			ppm
Harmonic oscillation start voltage	V _{HHO}	CG=5pF (V _{SS})			-2.0	V
Allowable leak resistance	R _{LEAK}	Between OSC1 and V _{DD} , and between V _{SS} and OSC1	200			MΩ

*1: Items enclosed in parentheses () are those used when operating at heavy load protection mode.

E0C6002 (CR)

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-3.0V, R_{CR}=420kΩ, Ta=25°C)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation frequency dispersion	f _{OSC}		-20	65kHz	20	%
Oscillation start voltage	V _{STA}		-1.8			V
Oscillation start time	t _{STA}	V _{SS} =-1.8 to -3.5V		3		mS
Oscillation stop voltage	V _{STP}		-1.8			V

E0C60L02 (CR)

(Unless otherwise specified: V_{DD}=0V, V_{SS}=-1.5V, R_{CR}=420kΩ, Ta=25°C)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation frequency dispersion	f _{OSC}		-20	65kHz	20	%
Oscillation start voltage	V _{STA}		-1.2			V
Oscillation start time	t _{STA}	V _{SS} =-1.2 to -2.0V		3		mS
Oscillation stop voltage	V _{STP}		-1.2			V

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